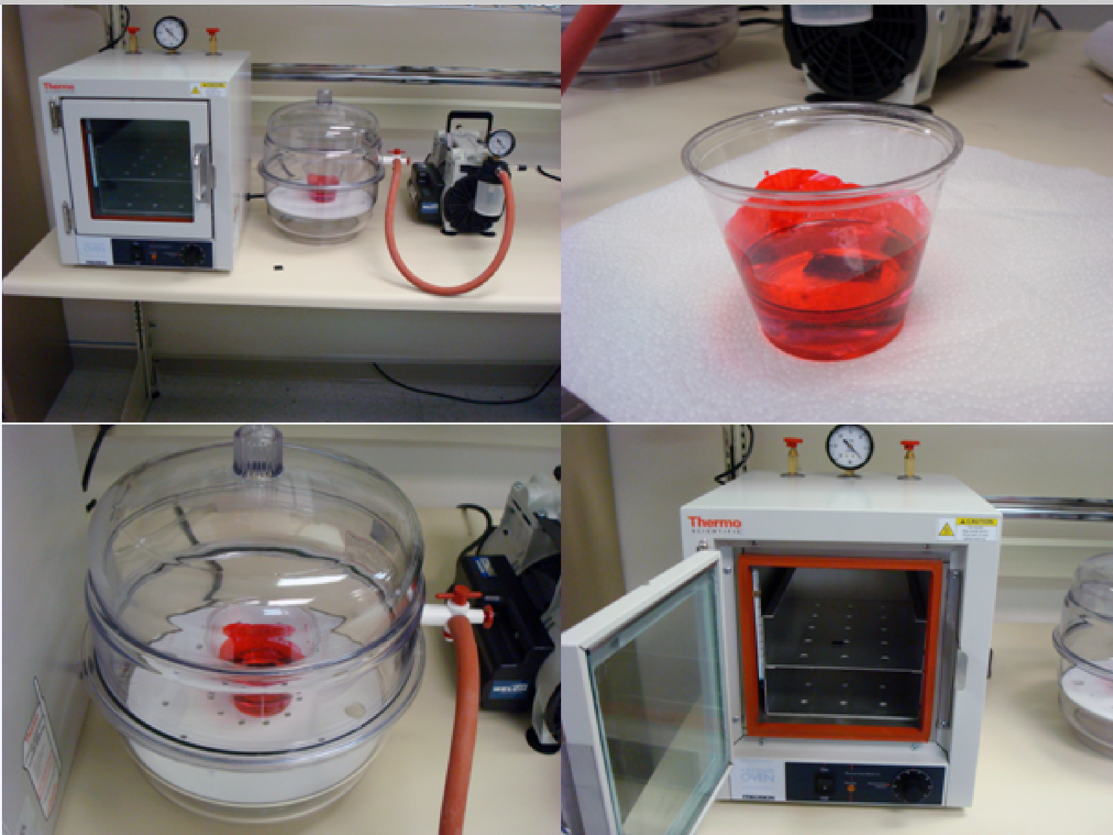
Cascade Engineering Services, Inc.

Dye and Pry Capabilities



Applications

Destructive failure analysis technique for delamination, voids or cracks in area array solder joints or other IC circuits in PCBs.